

9-19-05 11<sup>th</sup> 2811



ATTORNEY DOCKET NO: 70357

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : FINN et al.  
Serial No : 10/019,696  
Confirm. No : 3879  
Filed : November 2, 2001  
For : CHIP CARRIER FOR...  
Art Unit : 2811  
Examiner : Quang D. Vu  
Dated : September 15, 2005

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

The Examiner is requested to consider references cited in the corresponding European application procedure for the corresponding European application (Serial No. 00 936 667.5). In the corresponding European procedure an office action was issued on August 8, 2005. Because each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in the counterpart European application not more than three months prior to the filing of the Information Disclosure Statement, Applicants believe no fee is due.

The FR2756955 concerns a method for producing an electronic circuit (1) for an electronic chip card for non-contact data exchange with a reading device, said electronic circuit (1) comprising an antenna (10) for being coupled with said reading device and a semiconductor chip (20) connected to said antenna (10). The invention is characterized in that it consists of

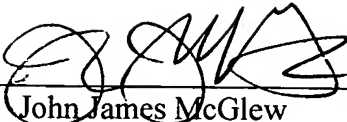
the following steps: a) producing on a plastic support-sheet (30) a coupling antenna (10) provided with two terminals (11, 12) for electrical connection; b) mounting on said terminals (11, 12) for electrical connection a semiconductor chip (20) with contact by protrusions (211, 221). The invention is applicable for making contact less cards. No translation of this French patent document is available to Applicants at this time. However, Applicants are attaching an abstract corresponding to the document.

The EP0391790 relates to the encapsulation of integrated circuit chips, in particular with a view to incorporating them in a chip card. The method of encapsulation comprises formation of a pre-blanked metal conductive grid (10), the formation of a pre-perforated plastic strip (20), the transferring of the strip onto the grid, the placement of an integrated circuit chip (26) into a perforation (22) of the strip, and the formation of electrical connections between the chip and zones (14) of the grid which are situated in perforations (24) of the strip. The perforations (22, 24) of the strip and the blanks of the grid are arranged in such a way that the strip covers over and plugs all the interstices (16) between conductors of the grid in the useful region corresponding to a module to be produced. When a protective resin is laid, the latter is confined and does not escape through the interstices of the grid. A plastic or metal ring defines the height dimension of the micro module. No translation of this French patent document is available to Applicants at this time. However, Applicants are attaching an abstract corresponding to the document.

Favorable consideration is requested.

Respectfully submitted  
for Applicant,

By:



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70357.24

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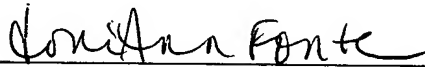
SHOULD ANY OTHER FEE BE REQUIRED, THE PATENT AND TRADEMARK OFFICE IS HEREBY REQUESTED TO CHARGE SUCH FEE TO OUR DEPOSIT ACCOUNT 13-0410.

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BY:



DATE: September 15, 2005



Form PTO-1449 U.S. Department of Commerce Sheet 1 of 1  
Patent and Trademark Office

LIST OF REFERENCES CITED  
BY APPLICANT  
(Use several sheets if necessary)

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U.S. PATENT

DOCUMENTS

Ex-aminer Document No. Date Name Class class Sub-Filing Date  
Initial


FOREIGN PATENT DOCUMENTS

Ex-aminer Document No. Date Country Class class Sub-Translation  
Initial Yes/No

	<u>FR 2 756 955 - A1</u>	<u>December 11, 1996</u>	<u>France</u>			<u>No</u>
	<u>EP 0 391 790 A1</u>	<u>April 3, 1990</u>	<u>Europe</u>			<u>No</u>

Quang D. Vu  
Examiner

Date Considered